

# Multilayered Functional Insulation System (MFIS) for AC Power Transmission in High Voltage Hybrid Electrical Propulsion

Team Lead Maricela Lizcano, PhD  
Research Materials Engineer  
Materials Chemistry and Physics Branch  
NASA Glenn Research Center  
Cleveland, OH 44135

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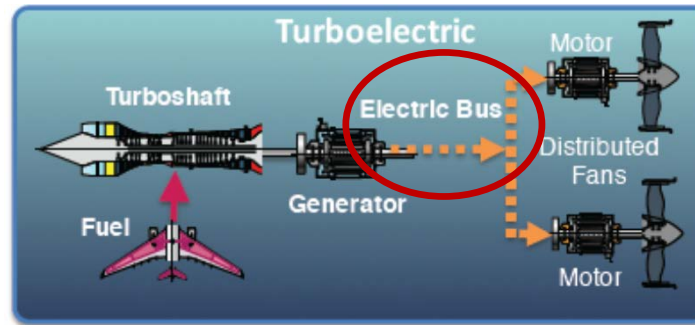
# Aeronautics Research Mission Directorate (ARMD) Transformative Aeronautics Concepts Program

Our project was a sub-task of the High Voltage Hybrid Electric Propulsion task, (PI Ray Beach and Co-PI Linda Taylor). It was supported by NASA's Convergent Aeronautics Solutions (CAS) Project. The sub-task was a 2 year feasibility study to investigate the possibility of improving the performance of insulation materials used to protect high voltage power transmission from electrical arcing events.

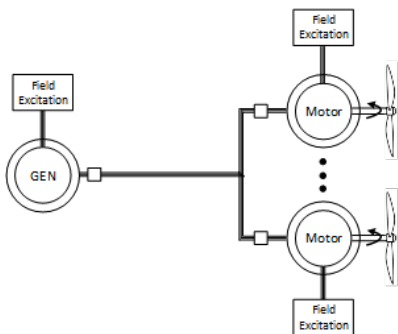
The project has been transitioned to the Transformational Tools and Technology (T<sup>3</sup>) Project to continue developing innovative concepts for future hybrid electric aircraft. Both CAS and T<sup>3</sup> are part of NASA's Transformative Aeronautics Concept Program.

<https://www.nasa.gov/aeroresearch/programs/tacp>

# Lightweight High Voltage Power Transmission



## High Voltage Hybrid Electric Propulsion (HVHEP) Architecture



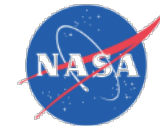
Future Aircraft will require ~20 MW power distribution

High Voltage,  $V_{AC_{max}} = 20 \text{ KV}$

Must Design for  $> 40 \text{ KV}$

Variable Frequency (400-4000 Hz)

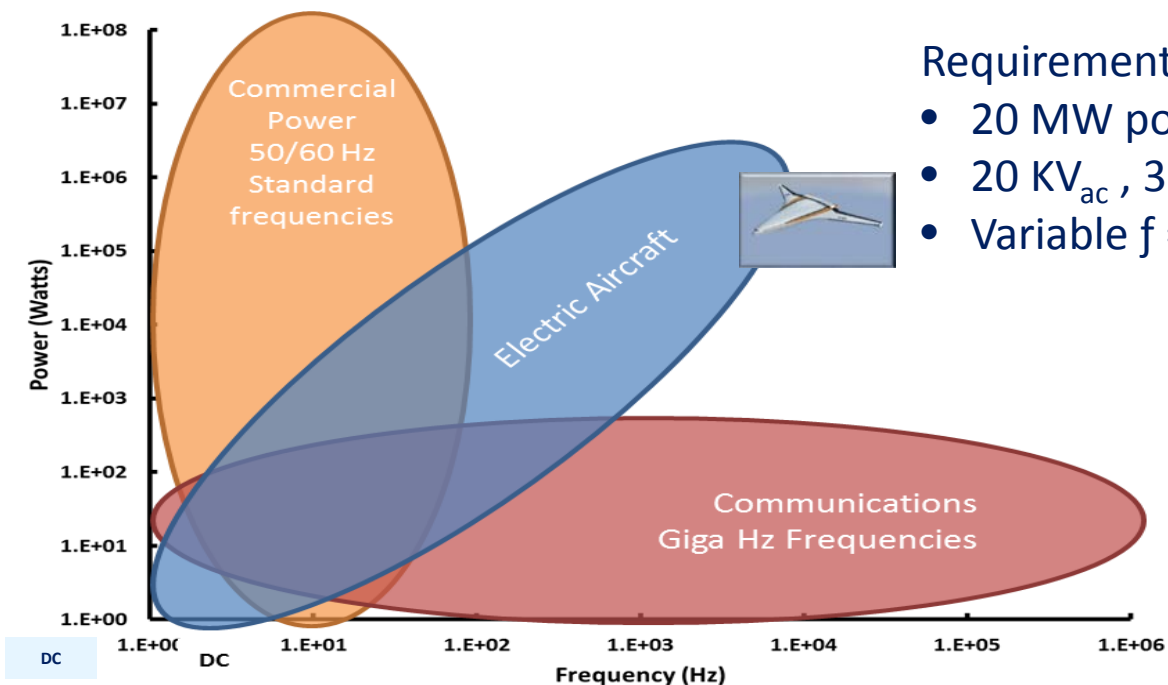




# Power Distribution and Transmission Technology

## Notional Current Technology Description

Combination of power and frequency make this a unique application space.  
Current high voltage cable technology is not suitable for high altitude operation.

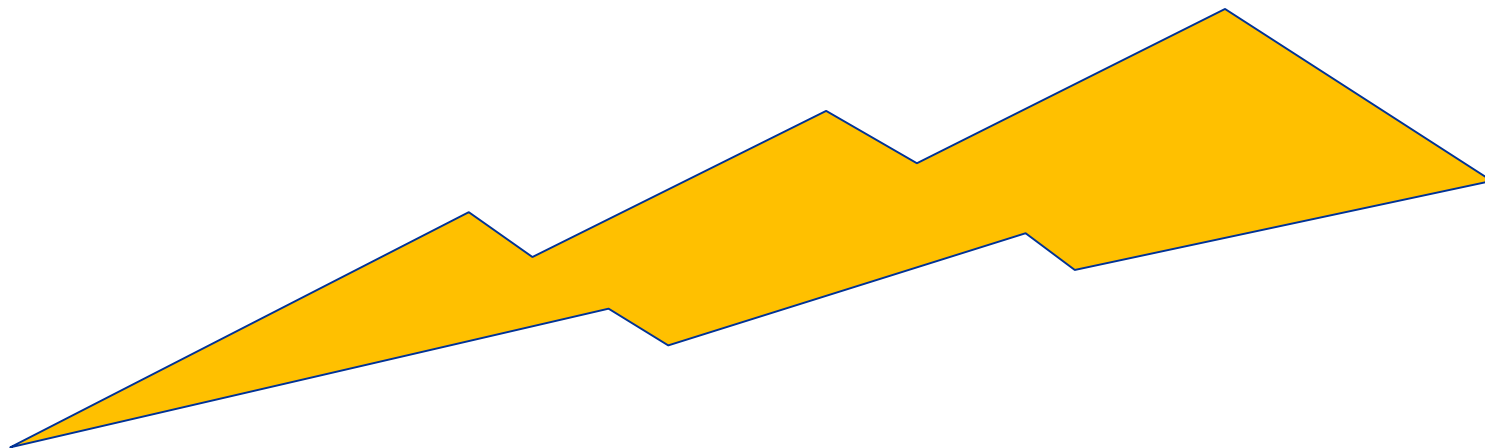


### Requirements

- 20 MW power cable
- 20 KV<sub>ac</sub>, 3-phase
- Variable  $f = 400-4000$  Hz



# Electrical Arcing Events at High Altitude



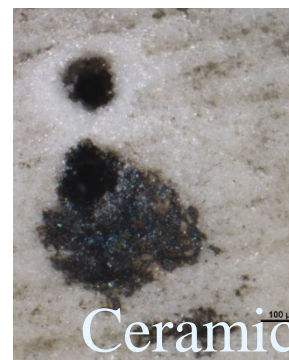
## Paschen's Curve

At high altitude electrical breakdown of an air gap or between uninsulated conductors become more prevalent. Voltages as low as 327 V will cause corona discharge and arcing events in air gaps. At higher frequencies, this minimum voltage decreases.

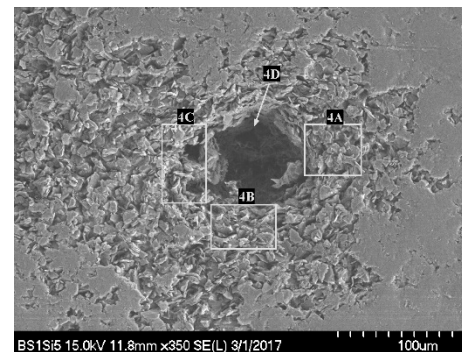
# Insulation Aging and Dielectric Breakdown

Electrical, thermal and mechanical stresses decrease the **performance life** of insulating materials

- Corona discharge contributors to material aging and failure.
  - material carbonization and material degradation from ozone generation
- Higher voltages and frequencies
  - Increased electrical and thermal stresses
- System operating temperature
  - Thermal cycling and thermal degradation



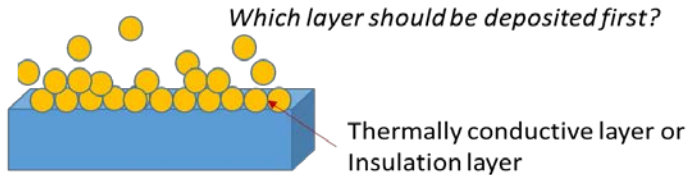
Damage from dielectric breakdown in ceramic and polymeric material



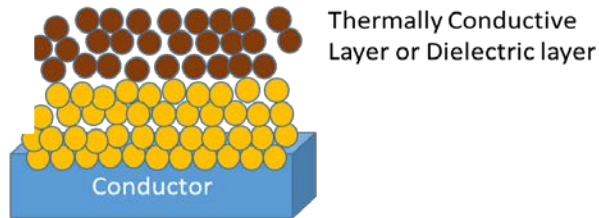
SEM of damage on ceramic



# Functional Insulation System Initial Concept Development

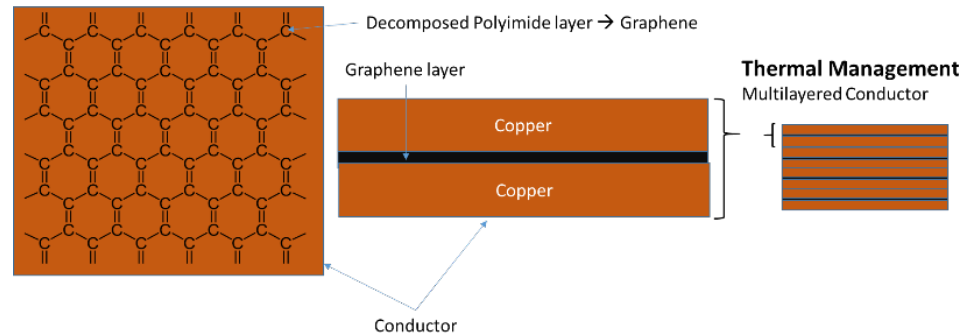


Physical Vapor Deposition

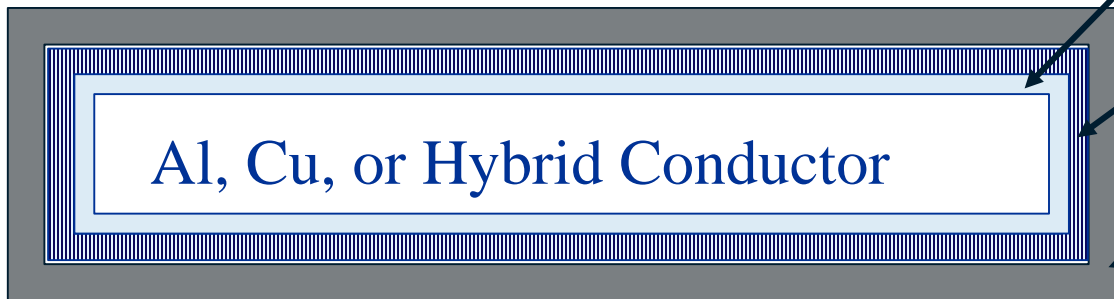


Layered Composite System  
Electrical Insulation and  
Thermal Management

Lightweight Composite Conductor



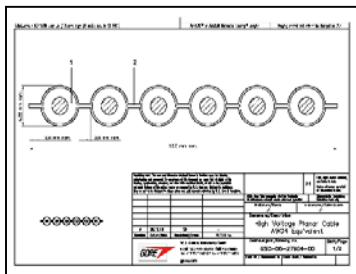
Basic Cable Construction



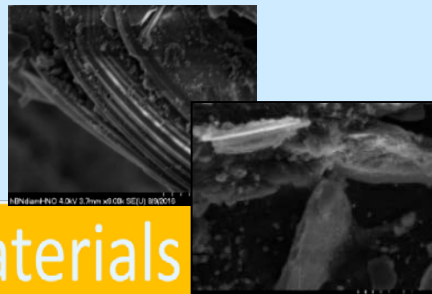
- SOA Dielectric Insulation
- EMI Shielding
- Protective Covering



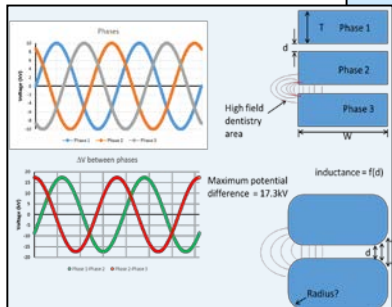
# Multidisciplinary Approach



Power Cable

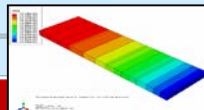


Materials R&D

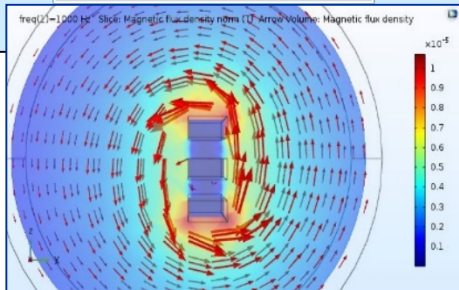
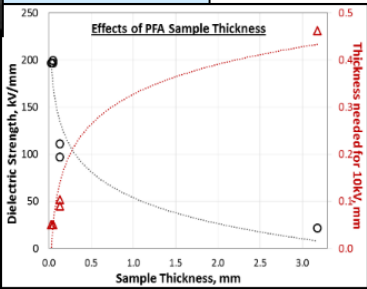


Physics

Modeling



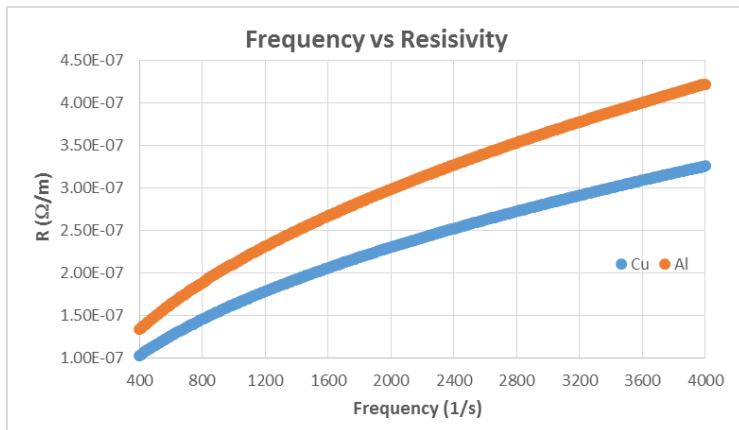
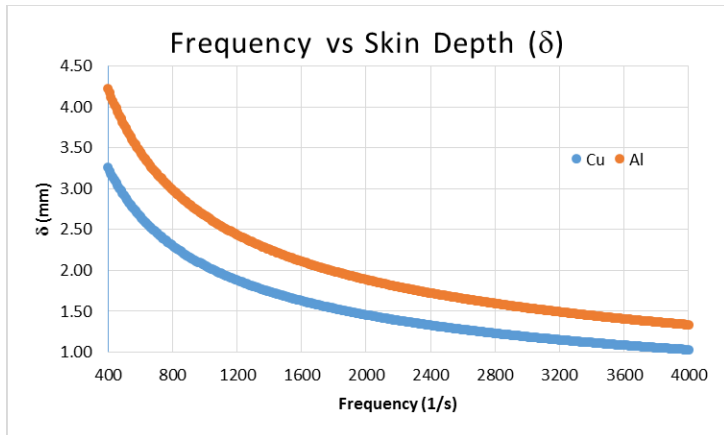
SOA Materials







# Physics



## Weight Comparison

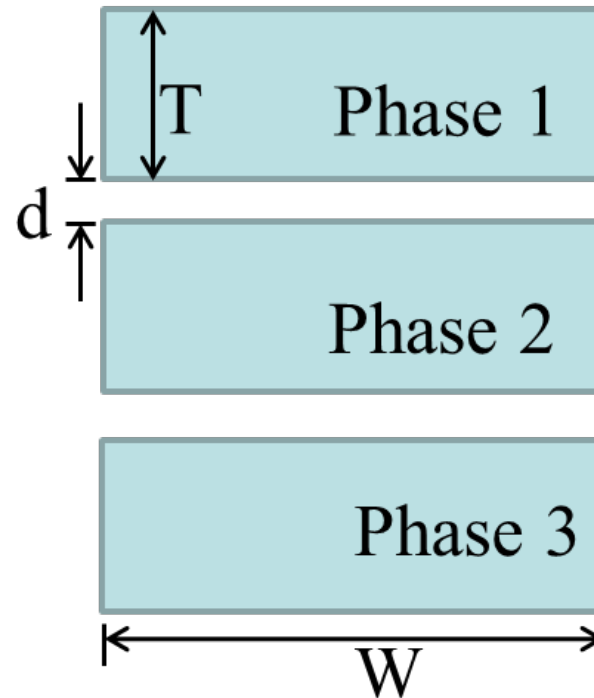
$$R = 3.26 \times 10^{-7} (\text{W/m})$$

$$\text{Cu} = 4.5 \text{ kg/m}$$

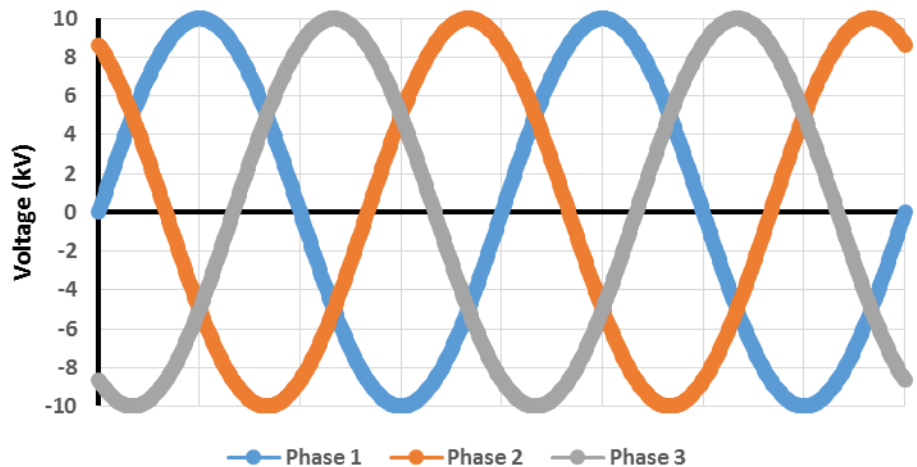
$$\text{Al} = 2.3 \text{ kg/m}$$

$$d_{\text{Cu-4kHz}} = 1.0 \text{ mm}, 5 \times d_{\text{Cu-4kHz}} = 5.0 \text{ mm}$$

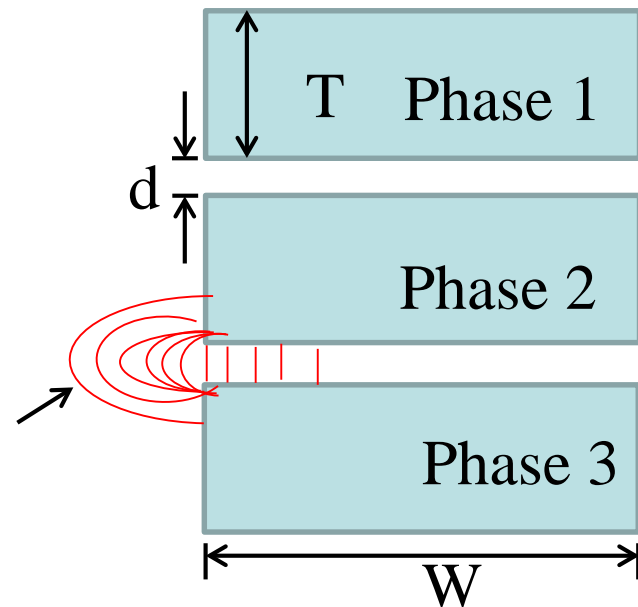
$$d_{\text{Al-4kHz}} = 1.3 \text{ mm}, 5 \times d_{\text{Al-4kHz}} = 6.5 \text{ mm}$$



Phases

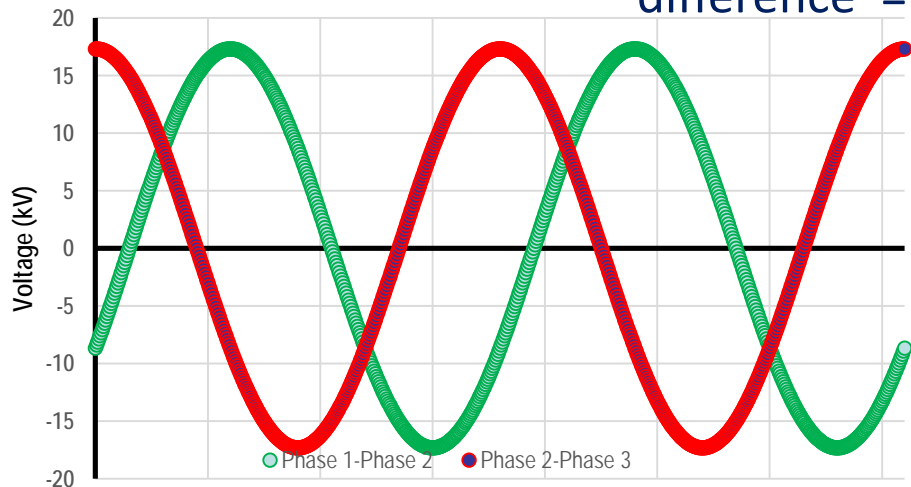


High field density area

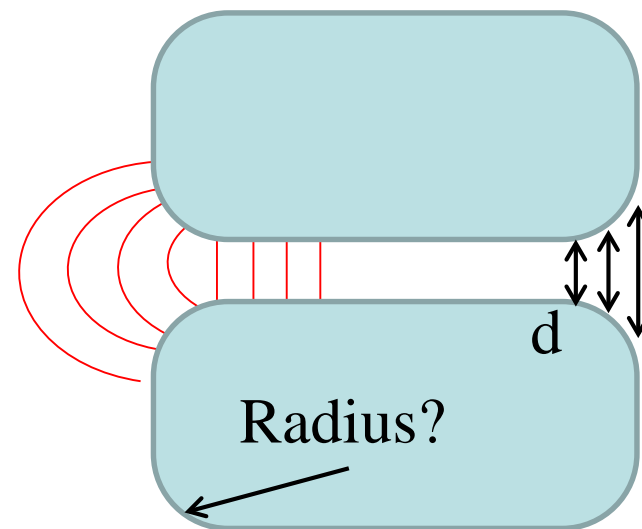


$\Delta V$  between phases

Maximum potential difference = 17.3kV



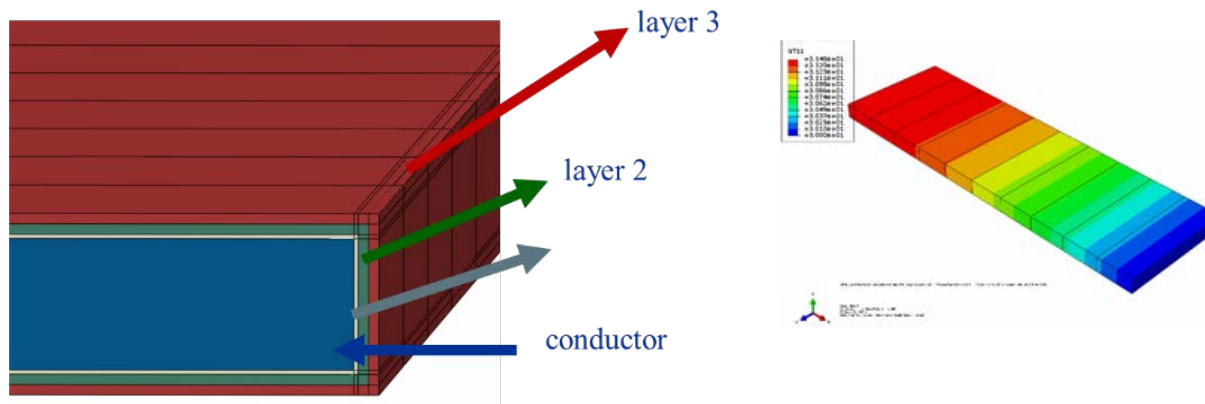
inductance = f(d)





# Electro-Thermal Modeling

The electro-thermal FE model of a “conductor+3 layers of insulation” was constructed. Application of AC current through a user-defined routine was successfully developed. Joule heating estimation for some chosen geometries was estimated for AC current (400 Hz and 4000 Hz).



Conductor Metal	Width (m)	Thickness (m)	Area m <sup>2</sup>	Length (m)	Voltage (V)	Amps (A)	AC/DC	Frequency Hz	Temp (C)
Cu	0.1	0.005	5.00E-04	20	1000	1000	AC	400	67
Cu	0.1	0.005	5.00E-04	20	5000	200	AC	400	31
Al	0.13	0.0065	8.45E-04	20	1000	1000	AC	400	64
Al	0.13	0.000325	4.23E-04	30	40000	125	AC	400	35
Cu	0.1	0.005	5.00E-04	20	1000	1000	AC	4000	65
Cu	0.1	0.005	5.00E-04	20	5000	200	AC	4000	31
Al	0.13	0.0065	8.45E-04	20	1000	1000	AC	4000	61
Al	0.13	0.000325	4.23E-04	30	40000	125	AC	4000	34



# Dielectric Breakdown Modeling

Model	Failure Mechanism	TF relationship
E-Model	Breakdown of bonds due to electrical and thermal energies	$\ln(TF) \propto \frac{\Delta E}{k_B T} - \gamma * E$
1/E-Model	Electron trapping leads to local current density	$t_{BD} = c * \text{Exp}\left(\frac{B + H}{E}\right)$
$\sqrt{E}$ -Model	Electron trapping leads to breakdown charge	$TF = B * \text{Exp}(-r\sqrt{E}) * (-\ln(1 - F))^{1/m}$
Power Model ( $E^m$ )	Breakdown of hydrogen bonds introduced to lattice	$TF \propto t_0 * E^{-m}$
$E^2$ -Model	Oxidizing copper leads to copper ions in dielectric. Makes dielectric conductive	$TF = A * \text{Exp}\left(\frac{E_a - \gamma E_{app}^2}{k_B t}\right) * t_{mass}$

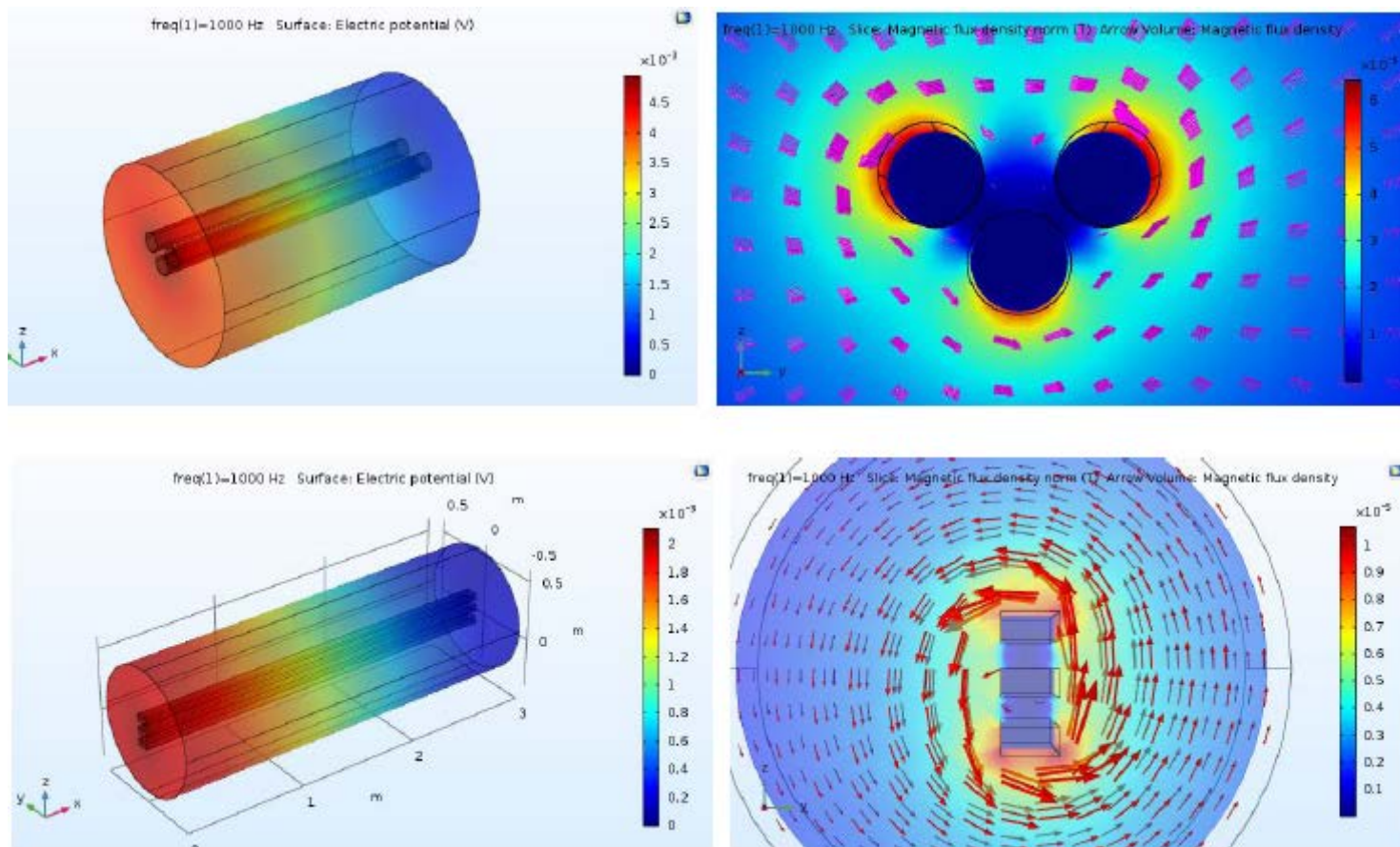
## Time Dependent DB vs Voltage Ramp DB

TDDDB- low voltage, failure over long period of time

VRDB- voltage ramping, happens quickly



# EM Field Modeling



EM field interactions between conductors will change  
With conductor geometry and spacing.



# Dielectric Insulation Materials Testing Capabilities

## Dielectric Test Rig Specifications

	AC	DC	
<b>Output voltage AC :</b> Vmax.	60.00	84.84	kV
Vmin.	1.800	2.545	kV
Regulation:	+/-0.4	0.57	kV
Resolution:	0.017	0.024	kV
<b>Ramp Rate:</b> max.	5.500	7.777	kV/s
(Average speed) min.	1.100	1.555	kV/s

## Electrode Test Fixtures

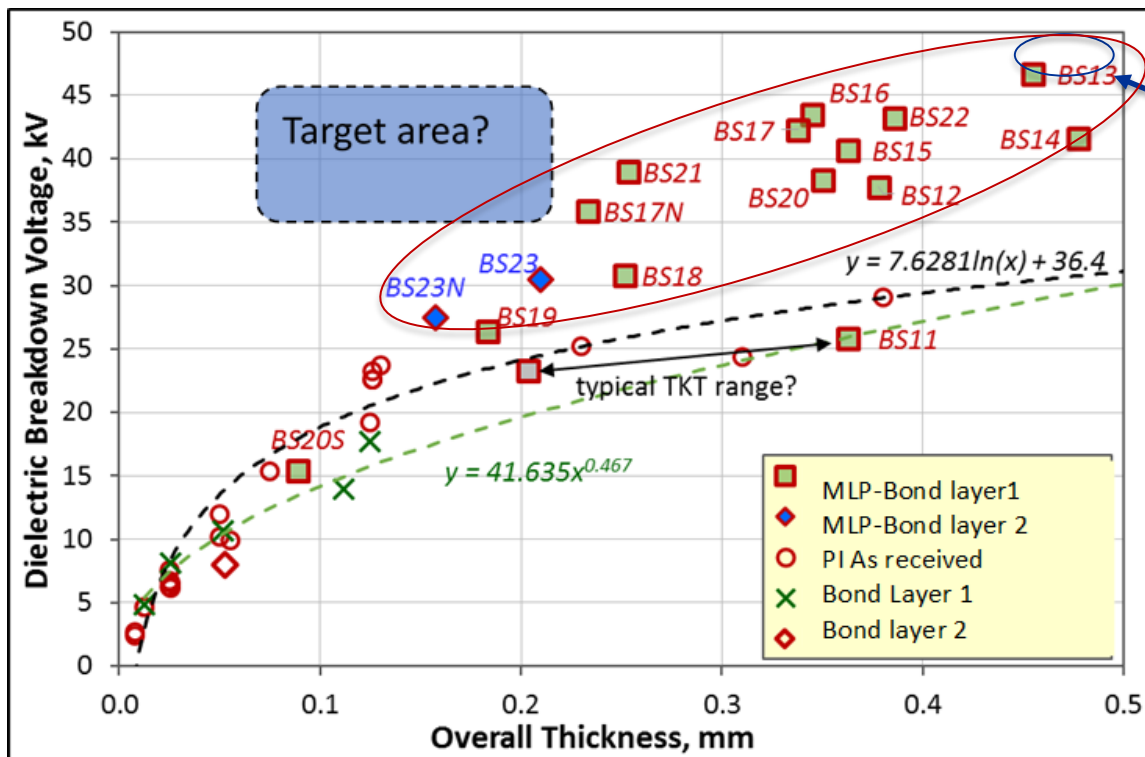
Seven electrode test fixtures (T1-T7) available according to ASTM D149-09 for Standard Test Method for Dielectric Breakdown Voltage and Dielectric Strength of Solid Electrical Insulating Materials at Commercial Power Frequencies



Eaton High Voltage Test Set  
Located at NASA GRC 106:B10



# SOA and Functional Insulation System Testing



As Received Kapton trend line

$$y = 7.628 \ln(x) + 36.4$$

$$x = e^{((y-36.4)/7.628)}$$

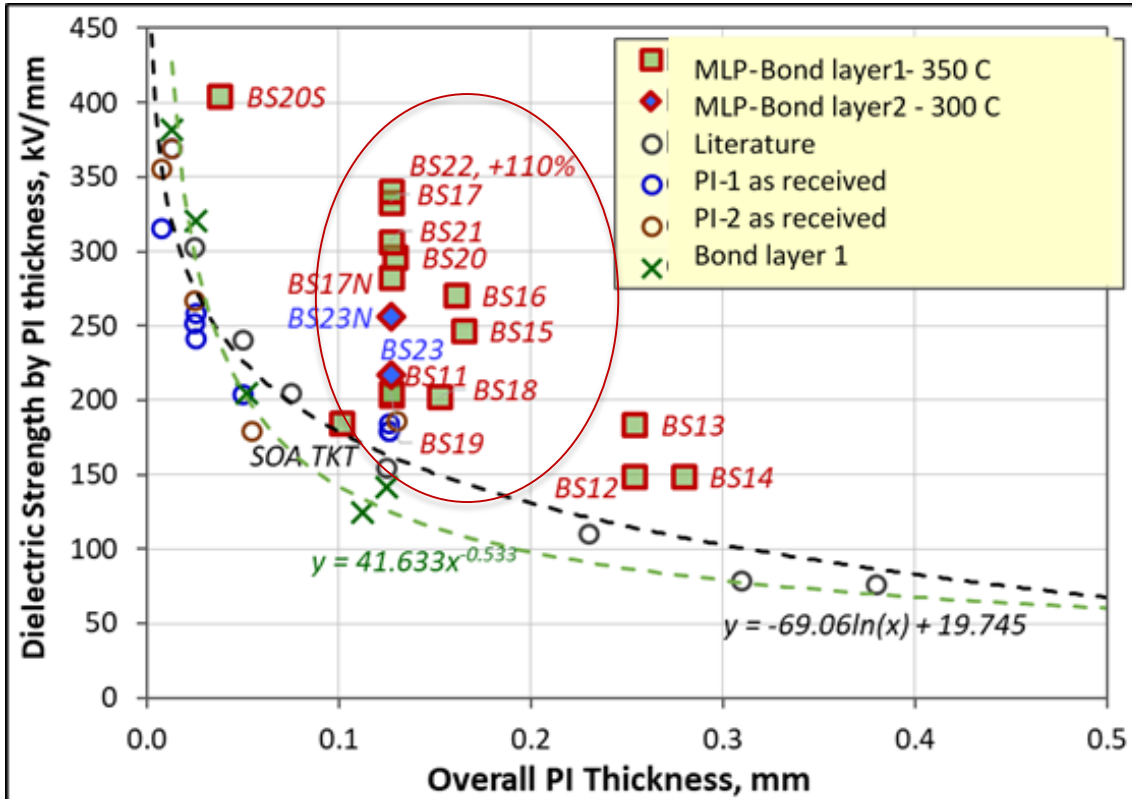
$$x = e^{((46-36.4)/7.628)}$$

$$x = 3.52 \text{ mm Kapton thickness}$$

**86% decrease in insulation thickness.** This also decrease volume of the cable.



# Improvement in Dielectric Strength

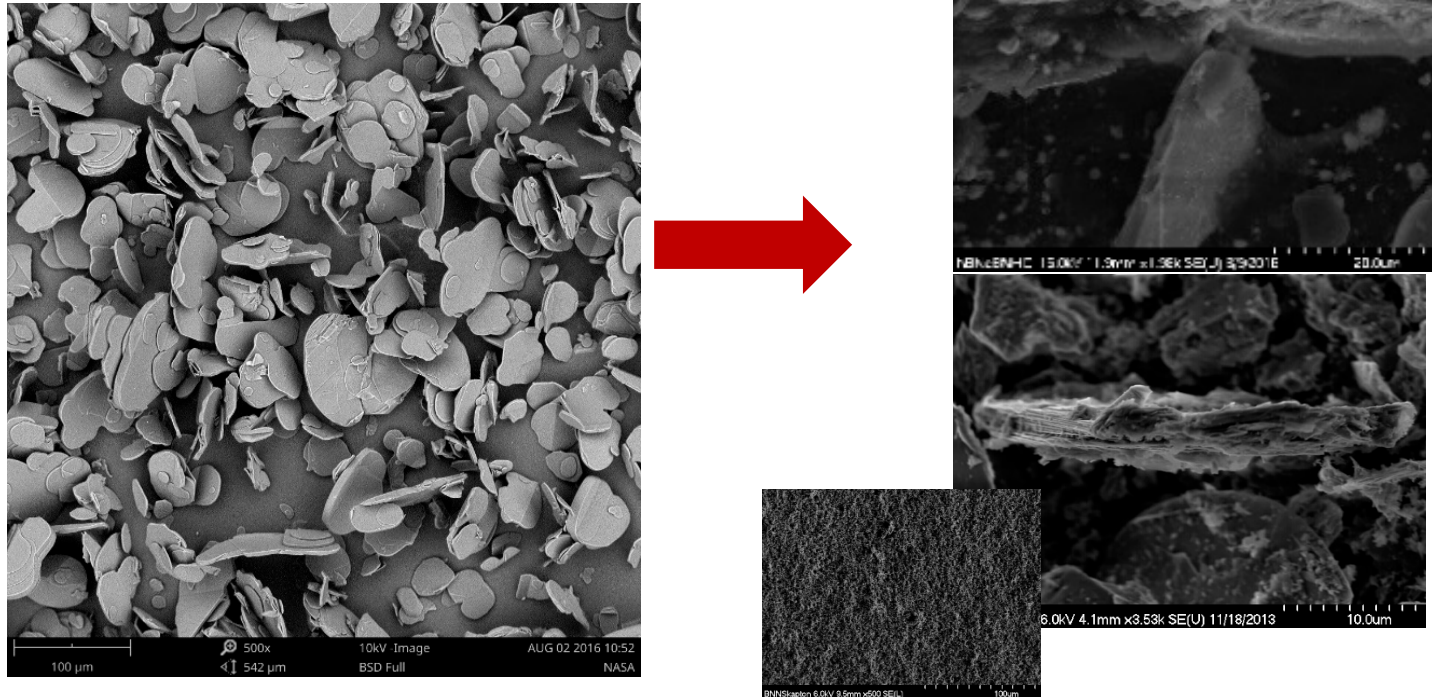


Compared to as received Kapton, the dielectric strength of the functional insulation system also increases significantly for equivalent thickness.

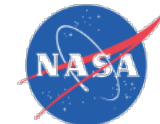




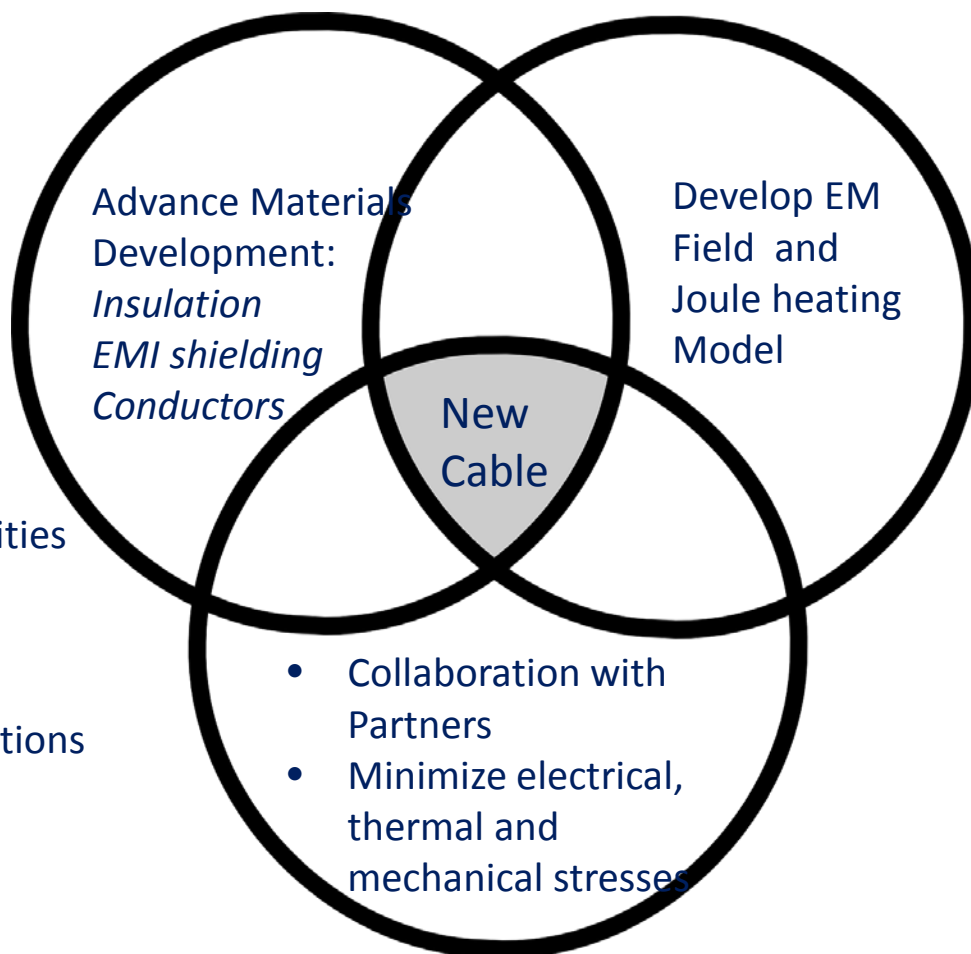
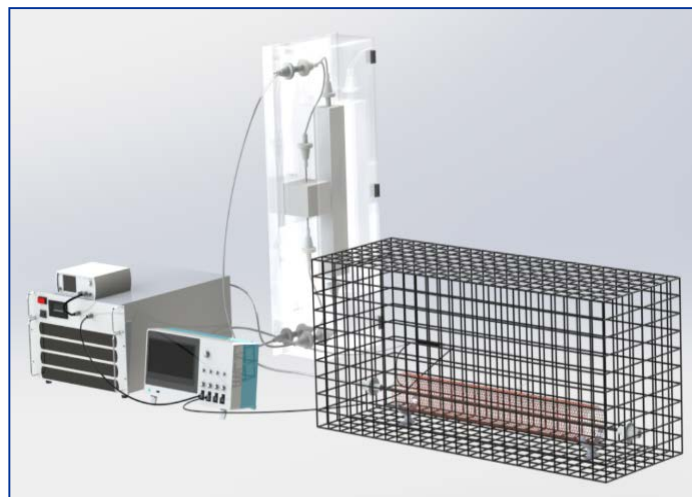
# Materials R&D



Chemically tailoring the properties of a ceramic material to enhance dielectric and thermal properties of composites we can add functionality to cable insulation.



## Next Steps: Transformational Tools and Technology



- Continue to foster and collaborate with universities and industry
- Build Test Chamber
- Cable design, conductor geometry based on modeling tools provides design and material options
- Advanced **lightweight** materials
  - Corona resistant materials
  - EMI Shielding
  - Lightweight composite conductors
  - Advanced dielectric insulators
- Minimize environmental stresses on materials will increase performance life



## 5 Year Objectives

- Materials R&D: Insulation, EMI shielding, advanced conductor
- Build HVHF Environmental Test Chamber Capability
- Draft Standard Test Method of High Altitude High Voltage Power Transmission
- Development Integrated Modeling Tool
- Demonstration of HVHF Power Transmission System



# Team Members

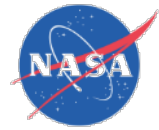
Andy Woodworth  
Eugene Shin  
Tiffany Williams  
Paria Naghipour  
Ben Kowalski  
Janet Hurst  
Fran Hurwitz  
Dan Scheiman

## *Student Interns*

Jeremey Walker UH  
Taylor Ceh OSU  
Angel Chavez UC-Irving  
Mitsuo Inukai UTRGV  
Astrid Rodriguez UTRGV  
Victor Nguyen UAz  
Jonathan Li Yale

*Thanks Team!*

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# Questions?